

DATA SHEET



GPMD8102A

Qi Compliant Wireless Power Receiver

APR. 05, 2017

Version 1.0

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1. GENERAL DESCRIPTION

GPMQ8102A is a single-chip, advanced, flexible, secondary-side device for wireless power transfer in portable applications capable of providing up to 4 W. It has high integration, high efficiency, low power consumption.

GPMQ8102A receiver the power that uses the near field electromagnetic induction principle, the power transfer is through coupling between the transmitter coil (primary) and receiver coil (secondary), Global feedback is established from the secondary to the primary to control the power transfer process using the Qi V1.2.2 protocol.

GPMQ8102A integrated a low resistance synchronous rectifier (AC to DC), low-dropout regulator (LDO), digital control, and accurate voltage and current loops to improve the high efficiency and decrease the power dissipation.

GPMQ8102A also integrated a digital controller that comply with the WPC V1.2.2 standard, it can calculate the amount of power received by the mobile device, the controller then communicates this information to the transmitter to allow the transmitter to determine if a foreign object is present within the magnetic interface and introduces a higher level of safety within magnetic field. This foreign object detection (FOD) method is part of requirement under the WPV V1.2.2 specification.

GPMQ8102A Output stage is LDO, the output voltage is adjusted dynamically according to the output current to achieve the best transient and efficiency.

GPMQ8102A supports I²C internal register configuration, The output voltage and current can be flexibly configured according to the application case.

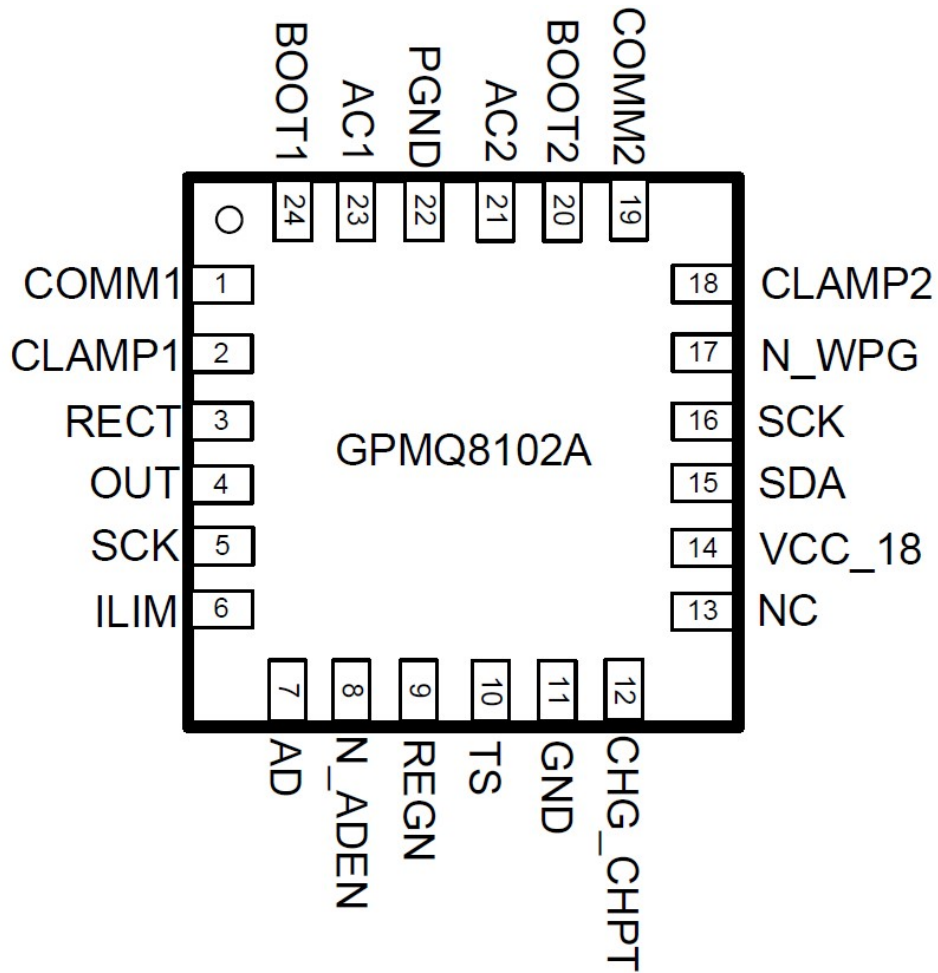
2. FEATURES

- Integrated Wireless Power Supply Receiver Solution
 - High Efficiency Full Synchronous Rectifier
 - Output Voltage Conditioning
 - WPC Qi V1.2.2 Compliant communication
 - Control
 - Single IC Required Between RX Coil and Output
- WPC Qi V1.2.2 FOD Function
- Support I²C Internal Register Configuration
 - Output Current -VRECT
 - Output Current - IOUT
- Dynamic Rectifier VRECT
 - Improve the Load Transient Response
 - Optimize the dynamic efficiency for full load output
- Rectifier Overvoltage Clamp (V_{OVP}=15V)
- Support 20 V Maximum Input
- Over Temperature, Over Voltage and Over Current Protection
- Open Drain LED Output Indication
- Multifunction NTC and Temperature Monitoring, Charge Complete and Fault Host Control
- Compatible with Adapter and USB Input Application
- QFN 4mm*4mm 24Pin Package

3. SIGNAL DESCRIPTIONS
3.1. PIN Description

Pin Name	RHL	I/O	Description
AC1	23	I	AC input from receiver coil.
AC2	21	I	
BOOT1	24	O	Bootstrap capacitors for driving the high side FETs of the synchronous rectifier. Connect a 10nF capacitor from BOOT1 to AC1 and BOOT2 to AC2.
BOOT2	20	O	
RECT	3	O	Filter capacitor for the inter rectifier. Connect to PGND with 22uF capacitor.
OUT	4	O	Power output, delivers power to the load.
COMM1	1	O	Open drain output used to communication with TX coil by varying reflected impedance. Connect through a capacitor to either AC1 or AC2 for capacitive load modulation.
COMM2	19	O	
CLAMP1	2	O	Open drain FETs which are utilized for over voltage AC clamp protection
CLAMP2	18	O	
AD	7	I	Adapter or USB input.
N_ADEN	8	O	Push-pull driver for external PFET connecting AD and OUT. This voltage tracks approximately 4V below AD when effective voltage is present at AD pin. Float this pin if unused.
PGND	22		Power ground.
GND	11		Analog ground.
ILIM	6	I/O	Programming pin for the over current limit. Connect external resistor to GND. Sizing the RILIM with the following equation: $RILIM = 1.2K/IMAX$, IMAX is the Maximum output current.
FOD	5	I	Input for receiver power measurement.
TS	10	I	Temperature Sense (TS) functionality. If an NTC function is not desired, connect to PGND with a 10-kΩ resistor, See Temperature Sense Resistor Network (TS) for more details.
VCC18	14	O	1.8V power output. Connect to GND with 1uF capacitor
REGN	9	O	5V power output. Connect to GND with 1uF capacitor.
SDA	15	I/O	I ² C data pin.
SCL	16	O	I ² C clock pin.
N_WPG	17	O	Active when output current is being delivered to the load, Open Drain output, OUT pin connects to the pin with a resistor and a LED.
CHG_CMPT	12	I	Charging indicator from load system.
NC	13		NC

3.2. PIN Map



24 Pin QFN Top View

4. ELECTRICAL SPECIFICATIONS

4.1. Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)

Item(V/I)	Pin Name	Min	Max	Unit
Input Voltage	AC1,AC2	-0.8	20	V
	RECT, COMM1,COMM2, OUT, CLAMP1, CLAMP2, N_WPG	-0.3	20	V
	BOOT1, BOOT2	-0.3	26	V
	AD, N_ADEN	-0.3	20	V
	FOD, ILIM, TS, CHG_CMPT, SDA, SCL	-0.3	7	V
Input Current	AC1,AC2		1.5	A
Output Current	OUT		1	A
Sink Current	COMM1, COMM 2, CLAMP1, CLAMP2		500	mA
	N_WPG		15	mA
ESD	HBM		2	KV
	CDM		500	V

1: All voltages are with respect to the VSS terminal, unless otherwise noted.

2: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

4.2. Thermal Information

Symbol	Description	Value	A
θ_{JA}	Thermal Resistance Junction to Ambient	35	$^{\circ}\text{C}/\text{W}$
θ_{JC}	Thermal Resistance Junction to Case	30	$^{\circ}\text{C}/\text{W}$
θ_{JB}	Thermal Resistance Junction to Board	2.4	$^{\circ}\text{C}/\text{W}$
T_J	Operating Junction Temperature	0 to +125	$^{\circ}\text{C}$
T_A	Ambient Operating Temperature	0 to +85	$^{\circ}\text{C}$
TSTG	Storage Temperature	-55 to +150	$^{\circ}\text{C}$
TLEAD	Lead Temperature (soldering, 10s)	300	$^{\circ}\text{C}$

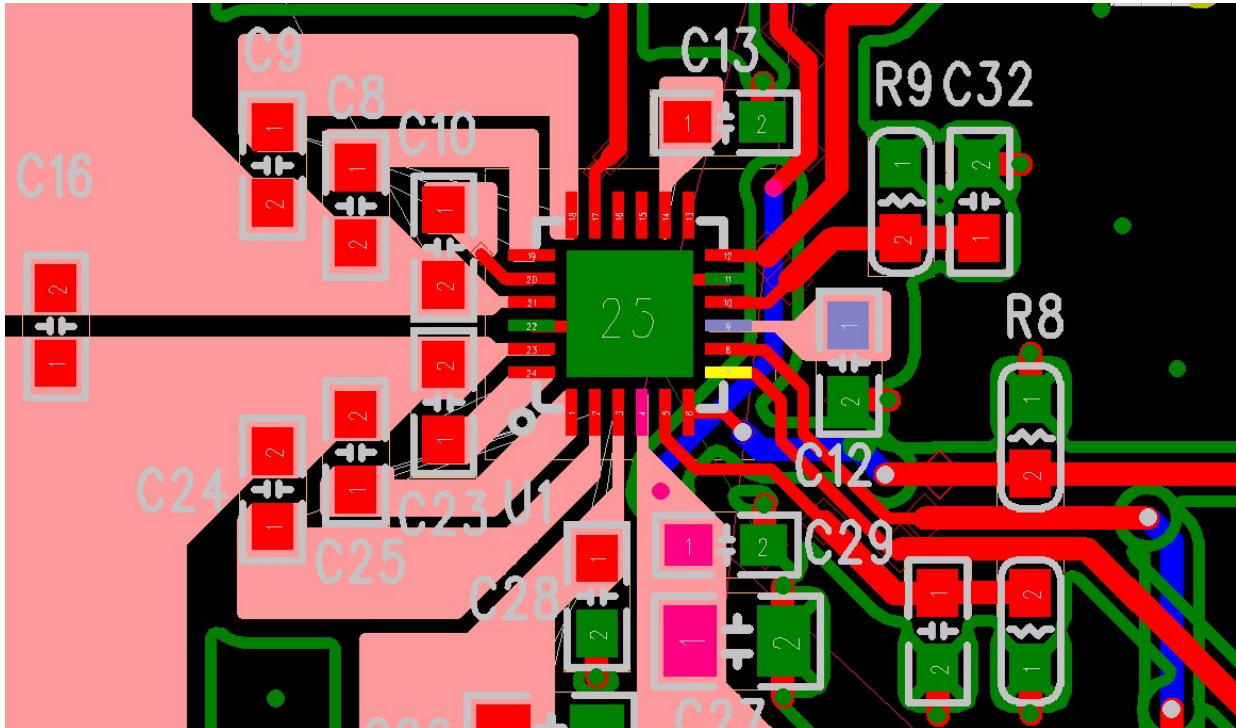
4.3. Electrical Characteristics

Over operating free-air temperature range, -40 to 85 $^{\circ}\text{C}$

Parameter		Test Condition	Min	Typ	Max	Unit
RECT						
$V_{\text{RECT-UV}}$	V_{RECT} Under Voltage lock-out	V_{RECT} : 0V \rightarrow 3.3V	2.9	3	3.1	V
	Hysteresis on UV			0.25		
$V_{\text{RECT-CLAMP}}$	V_{RECT} Over Voltage lock-out	V_{RECT} : 5V \rightarrow 16V	14.15	15	15.5	V
	Hysteresis on OV			6		
$V_{\text{RECT-REG}}$	Dynamic V_{RECTV} Threshold1	$I_{\text{LOAD}} < 0.1 \times I_{\text{MAX}}$		$V_{\text{OUT}}+2$		V
	Dynamic V_{RECTV} Threshold2	$0.1 \times I_{\text{MAX}} < I_{\text{LOAD}} < 0.2 \times I_{\text{MAX}}$		$V_{\text{OUT}}+1.5$		
	Dynamic V_{RECTV} Threshold3	$0.2 \times I_{\text{MAX}} < I_{\text{LOAD}} < 0.4 \times I_{\text{MAX}}$		$V_{\text{OUT}}+0.5$		
	Dynamic V_{RECTV} Threshold4	$I_{\text{LOAD}} > 0.4 \times I_{\text{MAX}}$		$V_{\text{OUT}}+0.2$		
$I_{\text{LOAD-HYS}}$	ILOAD Hysteresis for dynamic V_{RECT} as a% of I_{MAX}			4%		
$V_{\text{RECT-DPM}}$	Rectifier under voltage protection, restrict I_{OUT} at		3.2	3.3	3.4	V

Parameter		Test Condition	Min	Typ	Max	Unit
	V _{RECT-DPM}					
Quiescent Current						
I _{RECT}	Active IC quiescent current consumption at V _{RECT}	I _{LOAD} =0		8	10	mA
		I _{LOAD} =300mA		2	3	
I _Q	Quiescent current at the OUT when wireless power is disable	OUT=4.2V		10	15	μA
ILIM Short Current						
I _{OUT-CL}	Maximum output current limit	Maximum I _{LOAD} that will be delivered for 1mS when I _{LIM} is Short			1.5	A
OUTPUT						
K _{IMAX}	Current programming factor for the hardware protection	K _{IMAX} = R _{LIM} × I _{MAX}	1100	1200	1300	AΩ
ACC _{ILIM}	Current limit accuracy	V _{OUT} =3.8V, I _{LOAD} =0.8A, -20°C-125°C	-7		7	%
TS						
V _{TS}	Internal TS Bias voltage	I _{TS} < 100uA	2	2.2	2.4	V
V _{COLD}	Rising threshold	V _{TS} : 50%→60%	56.5	58.7	60.8	%V _{TS}
	Falling hysteresis			2		
V _{HOT}	Falling threshold	V _{TS} : 20%→15%	18.5	19.6	20.7	
	Rising hysteresis			3		
R _{TS}	V _{TS} output impedance		18	20	22	kΩ
t _{DB-TS}	Deglitch time for TS comparators			10		ms
Rectifier						
I _{LOAD-FULL}	IOUT at which the synchronous rectifier enters half-synchronous mode	I _{LOAD} : 0mA→200mA	105	125	155	mA
	Hysteresis			25		
R _{ON}	Impedence of rectifier FET			100		mΩ
Thermal Protection						
T _{J-OFF}	Thermal shutdown temperature			155		°C
	Thermal shutdown hysteresis			40		

6. LAYOUT EXAMPLES



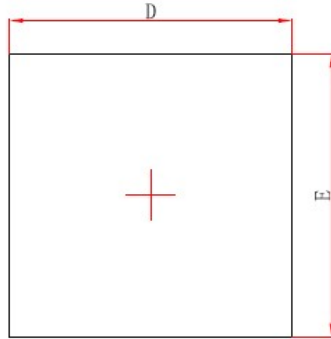
Top layer view

7. PACKAGE / ORDERING INFORMATION

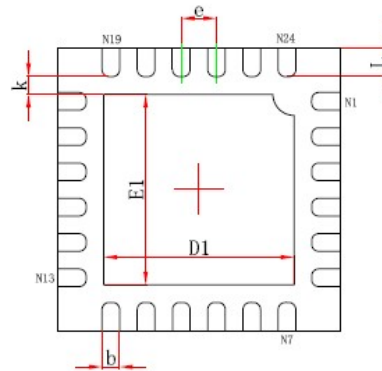
7.1. Ordering Information

Product Number	Package Type
GPMQ8102A	QFN24

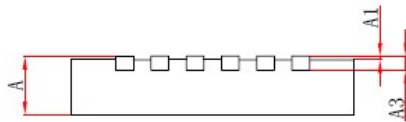
7.2. Package Information



Top View



Bottom View



Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	3.924	4.076	0.154	0.160
E	3.924	4.076	0.154	0.160
D1	2.600	2.800	0.102	0.110
E1	2.600	2.800	0.102	0.110
k	0.200MIN.		0.008MIN.	
b	0.200	0.300	0.008	0.012
e	0.500TYP.		0.020TYP.	
L	0.324	0.476	0.013	0.019

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9. REVISION HISTORY

Date	Revision #	Description	Page
APR. 05, 2017	1.0	Original	